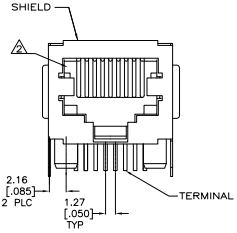
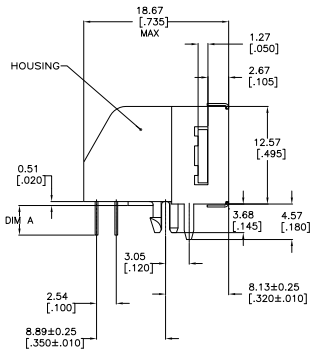
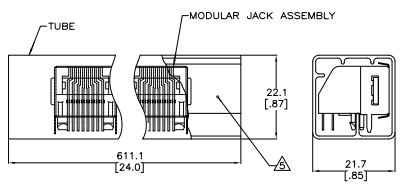
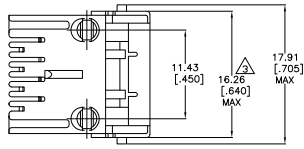


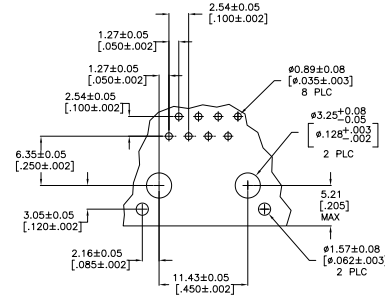
REV	DATE	DESCRIPTION	BY	APP'D
GP 00				
D		REVISED FOR ECO-08-017403		30AAL2009ZMR/PAK



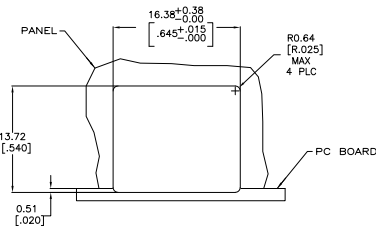
1. MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[014] THICK PHOS BRONZE PLATED WITH 1.27µm [0.00050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [0.00080] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.00050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [010] THICK COPPER ALLOY PLATED WITH 3.0µm [0.00120] MINIMUM THICK REFLOWED TIN
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - △ DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE
 - △ BULK PACKAGED IN A TRAY
 - △ 32 ASSEMBLIES PACKAGED PER TUBE. SEE DETAIL B



DETAIL B
SCALE 2:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

1.78-2.79 [0.09±0.02]	△	5555153-6
2.54-3.05 [0.11±0.01]	△	5555153-5
3.30-4.32 [0.15±0.02]	△	5555153-3
3.30-4.32 [0.15±0.02]	△	5555153-1
DIM A	PACKAGED	PART NUMBER

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REVISIONS: 108-1163, 114-2048, 100779

DESCRIPTION: MODULAR JACK ASSEMBLY, SHIELDED, B POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS

DATE: 11/1/08

CUSTOMER DRAWING: 5555153

SCALE: 2:1

REV: 1

APP'D: D